

WHAT IS CLAIMED IS:

1. A hybrid integrated circuit provided with:

a chip component with terminal electrodes formed at both ends, conductive wiring layers in which plurality of pads are provided in a manner corresponding to the terminal electrodes, an overcoat resin for covering the conductive wiring layers excluding the pads, and external electrodes which are electrically connected to the conductive wiring layers, wherein

a space portion is provided in the overcoat resin between the pads where the terminal electrodes of the chip component are attached by a brazing material.

2. A hybrid integrated circuit provided with:

a chip component with terminal electrodes formed at both ends, conductive wiring layers in which plurality of pads are provided in a manner corresponding to the terminal electrodes, an overcoat resin for covering the conductive wiring layers excluding the pads, and external electrodes made of a brazing material so as to be electrically connected to the conductive wiring layers, wherein

an insulating resin is provided between the pads where the terminal electrodes of the chip component are attached by a brazing material.

3. The hybrid integrated circuit of Claim 2, wherein as the insulating resin between the pads, an underfill resin is used.

4. A hybrid integrated circuit provided with:

a chip component with terminal electrodes formed at both ends, conductive wiring layers in which plurality of pads are provided in a manner corresponding to the terminal electrodes, an overcoat resin for covering the conductive wiring layers excluding the pads, and the external electrodes made of a brazing material so as to be electrically connected to the conductive wiring layers, wherein

a plating containing no tin is applied to the terminal electrodes of the chip component, and a brazing material to adhere the terminal electrodes to the pads is a brazing material with a higher melting point than that of the brazing material to form the external electrodes.

5. A hybrid integrated circuit comprising:

a chip component with a terminal electrodes formed at both ends, conductive wiring layers in which plurality of pads are provided in a manner corresponding to the terminal electrodes, and an overcoat resin for covering the conductive wiring layers excluding the pads, wherein

a conductive adhesive is provided on the pads, an insulating adhesive is provided between the pads, the chip component body is adhered to the overcoat resin by the insulating adhesive, and the terminal electrodes of the chip component are adhered to the pads by the conductive adhesive.

6. The hybrid integrated circuit of Claim 5, wherein

the insulating adhesive is disposed at a height to make contact with the chip component body in advance of the conductive adhesive.